

Title (en)

METHOD AND DEVICE FOR PRODUCING A BOND CONNECTION

Title (de)

VERFAHREN UND VORRICHTUNG ZUM HERSTELLEN EINER BONDVERBINDUNG

Title (fr)

PROCÉDÉ ET DISPOSITIF DE FABRICATION D'UNE LIAISON PAR SOUDAGE

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Application

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Abstract (en)

[origin: WO2008116761A1] The invention relates to a method for producing a bond connection between a conductor and a conductor substrate having a surface protection layer, particularly having an organic solder mask surface protection layer. According to the invention, prior to attaching the conductor (12) to the conductor substrate (3), the surface protection layer (2) is at least partially removed from the attachment site (15) by applying electromagnetic waves. The invention further relates to a device for producing a bond connection between a conductor and a conductor substrate having a surface protection layer, particularly having an organic solder mask surface protection layer. According to the invention, at least one device for generating electromagnetic waves is provided, which at least partially removes the surface protection layer (2) from the attachment site (15) prior to attaching the conductor (12) to the conductor substrate (3).

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